

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

Claim 1 (Currently Amended): A device comprising:

a substrate;

an interposer on said substrate;

a DC-to-DC converter secured on said interposer; and

spring contacts located between the interposer and substrate, wherein said contacts are located all around a die on the substrate.

Claim 2 (previously presented): The device of claim 1, wherein the substrate contains power sockets.

Claim 3 (previously presented): The device of claim 2, wherein the contact compresses into the power sockets to provide electrical connection.

Claim 4 (previously presented): The device of claim 1, wherein said contacts are located underneath the interposer.

Claim 5 (cancelled)

Claim 6 (previously presented): The device of claim 1, wherein the contacts are made of copper.